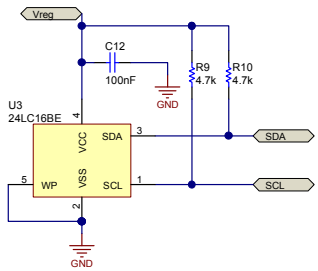
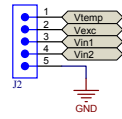


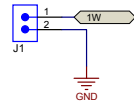
Calibration EEPROM



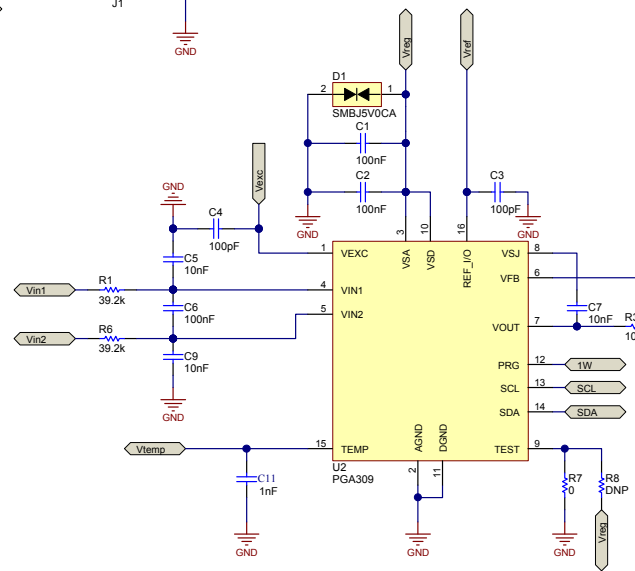
Bridge Sensor Connector



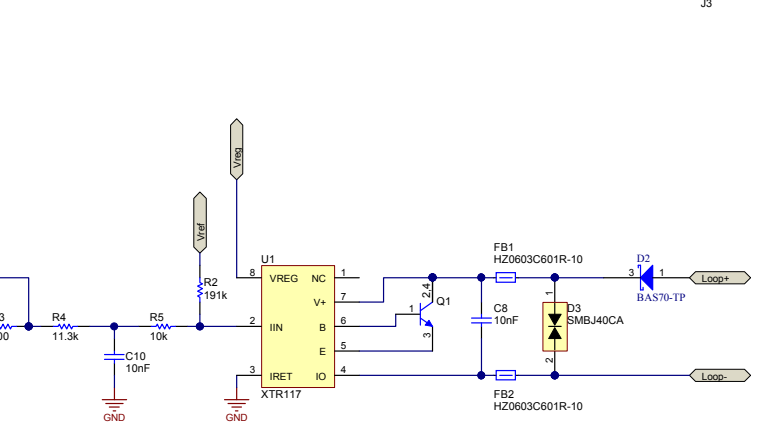
1W Connector



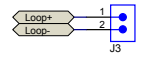
Sensor Signal Conditioning



4-20mA Transmitter



Loop Connector



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Number: XX###	Rev: E1	Designed for: Public Release	Mod. Date: 5/14/2013
SVN Rev: Not in version control	Assembly Variant: Variant name not interpreted	Project Title: Change in menu Project\Project Options\Parameters	
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Engineer: Enter name of project lead	Contact: http://www.ti.com/support	http://www.ti.com	



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